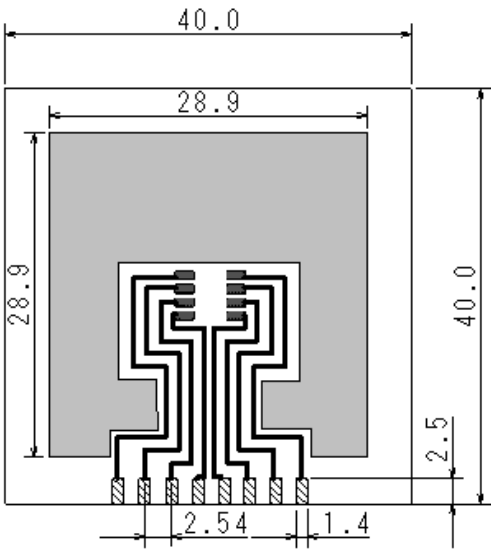


●**SOP-8 Power Dissipation**

Power dissipation data for the SOP-8 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
 - Board : Dimensions 40mm×40mm (1600mm² in one side)
 - Copper (Cu) traces occupy 50% of the board area
 - In top and back faces
- Material : Glass Epoxy (FR-4)
- Thickness : 1.6mm



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	650	153.85
85	260	

